ACM Research Delivered Its First High-Throughput Ultra Lith KrF Track System to a Leading Chinese Logic Wafer Fab Customer

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New Ultra Lith $_{KrF}$ Track System Delivers High-Throughput Performance with Proprietary Platform Design, Driving Advanced Process Control for Mature-node Lithography Applications

FREMONT, Calif., Sept. 07, 2025 (GLOBE NEWSWIRE) -- ACM Research, Inc. ("ACM") (NASDAQ: ACMR), a leading supplier of wafer and panel processing solutions for semiconductor and advanced packaging applications, today announced the launch of its first Ultra Lith $_{KrF}$ track system, designed to support front-end semiconductor manufacturing. The new system expands ACM's lithography product line and delivers high-throughput performance, advanced thermal control, and real-time process control and monitoring. The first system was shipped to a leading Chinese logic wafer fab customer in September 2025.

ACM's Ultra Lith $_{KrF}$ track system builds on the proven architecture and process achievements of ACM's ArF track platform, which successfully completed demo-line process verification with a leading Chinese customer in late 2024. That system demonstrated sub-angstrom-level coating uniformity, advanced thermal control, and ASML scanner-aligned CD matching—capabilities that provided the foundation for design optimization in the KrF platform.

"The launch of ACM's Ultra Lith $_{KrF}$ track system expands ACM's presence in front-end process equipment and reflects our commitment to address a broader range of lithography challenges," said Dr. David Wang, President and Chief Executive Officer of ACM. "KrF lithography remains essential for mature-node devices, which ACM believes represent a large and growing portion of global semiconductor output. By offering both ArF and KrF track systems, ACM enables seamless fab integration and greater manufacturing flexibility across diverse applications."

ACM's Ultra Lith $_{KrF}$ track system features a flexible process module configuration, including 12 spin coaters and 12 developers (12C12D), supported by 54 hot plates capable of low, mid, and high-temperature processing with industry-leading thermal uniformity. The system achieves throughput greater than 300 wafers per hour (WPH) and incorporates ACM's proprietary backside particle removal unit (BPRV) technology to minimize cross-contamination risk. In addition, the integrated wafer-scale outlier inspection (WSOI) unit enables real-time process variation detection and yield anomaly monitoring, enhancing process stability and production efficiency.

Forward-Looking Statements

Certain statements contained in this press release are not historical facts and may be forward-looking statements within the meaning of the Private Securities Litigation Reform Act of 1995. Words such as "plans," "expects," "believes," "anticipates," "designed," and similar words are intended to identify forward-looking statements. Forward-looking statements are based on ACM management's current expectations and beliefs and involve a number of risks and uncertainties that are difficult to predict and that could cause actual results to differ materially from those stated or implied by the forward-looking statements. A description of certain of these risks, uncertainties and other matters can be found in filings ACM makes with the U.S. Securities and Exchange Commission, all of which are available at www.sec.gov. Because forward-looking statements involve risks and uncertainties, actual results and events may differ materially from results and events currently expected by ACM. Readers are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the date hereof. ACM undertakes no obligation to publicly update these forward-looking statements to reflect events or circumstances that occur after the date hereof or to reflect any change in its expectations with regard to these forward-looking statements or the occurrence of unanticipated events.

About ACM Research, Inc.

ACM develops, manufactures and sells semiconductor process equipment spanning cleaning, electroplating, stress-free polishing, vertical furnace processes, track, PECVD, and wafer- and panel-level packaging tools, enabling advanced and semi-critical semiconductor device manufacturing. ACM is committed to delivering customized, high-performance, cost-effective process solutions that semiconductor manufacturers can use in numerous manufacturing steps to improve productivity and product yield. For more information, visit www.acmr.com.

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